

16

Electrical Specifications

This chapter specifies the following electrical behavior of the 21150:

- PCI electrical conformance
- Absolute maximum ratings
- dc specifications
- ac timing specifications

16.1 PCI Electrical Specification Conformance

The 21150 PCI pins conform to the basic set of PCI electrical specifications in the *PCI Local Bus Specification, Revision 2.1*. See that document for a complete description of the PCI I/O protocol and pin ac specifications.

16.2 Absolute Maximum Ratings

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The 21150 is specified to operate at a maximum frequency of 33 MHz at a junction temperature (T_j) not to exceed 125°C. Table 16–1 lists the absolute maximum ratings for the 21150. These are stress ratings only; extended exposure to the maximum ratings may affect the reliability of the device.

Table 16–1 Absolute Maximum Ratings

Parameter	Minimum	Maximum
T_j	—	125°C
T_a	0°C	70°C
P_{WC}	—	1.2 W @ 33 MHz
Storage temperature range	–55°C	125°C

16.3 DC Specifications

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Table 16–2 defines the dc parameters met by all 21150 signals under normal operating conditions.

Table 16–2 DC Parameters

Symbol	Parameter	Condition	Minimum	Maximum	Unit
V_{cc}	Supply voltage	—	3.0	3.6	V
V_{il}	Low-level input voltage ¹	—	–0.5	0.3 V_{cc}	V
V_{ih}	High-level input voltage ¹	—	0.5 V_{cc}	$V_{cc} + 0.5$ V	V
V_{ol}	Low-level output voltage ²	$I_{out} = 1500$ μ A	—	0.1 V_{cc}	V
V_{ol5V}	Low-level output voltage ³	$I_{out} = 6$ mA	—	0.55	V
V_{oh}	High-level output voltage ²	$I_{out} = -500$ μ A	0.9 V_{cc}	—	V
V_{oh5V}	High-level output voltage ³	$I_{out} = -2$ mA	2.4	—	V
I_{il}	Low-level input leakage current ^{1,4}	$0 < V_{in} < V_{cc}$	—	± 10	μ A
C_{in}	Input pin capacitance	—	—	10.0	pF
C_{IDSEL}	p_idsel pin capacitance	—	—	8.0	pF
C_{clk}	p_clk, s_clk pin capacitance	—	5.0	12.0	pF

¹Guarantees meeting the specification for the 5-V signaling environment.

²For 3.3-V signaling environment.

³For 5-V signaling environment.

⁴Input leakage currents include high-Z output leakage for all bidirectional buffers with tristate outputs.

Note

In Table 16–2, currents into the chip (chip sinking) are denoted as positive (+) current. Currents from the chip (chip sourcing) are denoted as negative (–) current.

16.4 AC Timing Specifications

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The next sections specify the following:

- Clock timing specifications
- PCI signal timing specifications
- Reset timing specifications
- **gpio** timing specifications
- JTAG timing specifications

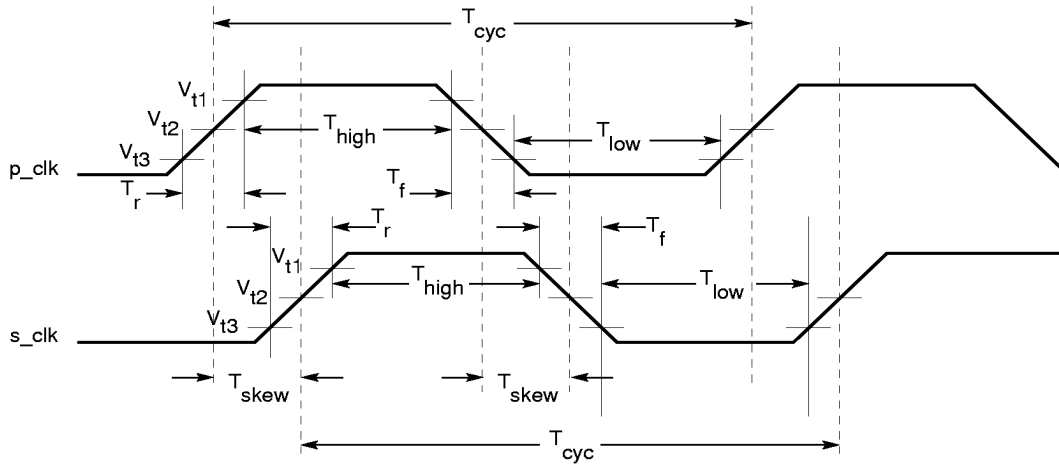
16.4.1 Clock Timing Specifications

The ac specifications consist of input requirements and output responses. The input requirements consist of setup and hold times, pulse widths, and high and low times. Output responses are delays from clock to signal. The ac specifications are defined separately for each clock domain within the 21150.

Figure 16–1 shows the ac parameter measurements for the **p_clk** and **s_clk** signals, and Table 16–3 specifies **p_clk** and **s_clk** parameter values for clock signal ac timing. See also Figure 16–2 for a further illustration of signal timing.

16.4 AC Timing Specifications

Figure 16–1 PCI Clock Signal AC Parameter Measurements



Note:

V_{t1} – 2.0 V for 5-V clocks; 0.5 V_{cc} for 3.3-V clocks

V_{t2} – 1.5 V for 5-V clocks; 0.4 V_{cc} for 3.3-V clocks

V_{t3} – 0.8 V for 5-V clocks; 0.3 V_{cc} for 3.3-V clocks

LJ-04738.A14

16.4 AC Timing Specifications

Table 16–3 PCI Clock Signal AC Parameters

Symbol	Parameter	Minimum	Maximum	Unit
T_{cyc}	p_clk , s_clk cycle time	30	∞	ns
T_{high}	p_clk , s_clk high time	11	—	ns
T_{low}	p_clk , s_clk low time	11	—	ns
	p_clk , s_clk slew rate ¹	1	4	V/ns
T_{sclk}	Delay from p_clk to s_clk	0	7	ns
T_{sclkr}	p_clk rising to s_clk_o rising	0	5	ns
T_{sclkf}	p_clk falling to s_clk_o falling ²	0	5	ns
T_{dskew}	s_clk_0 duty cycle skew from p_clk duty cycle ²	—	0.750	ns
T_{skew}	s_clk_0 <x> to s_clk_0 <y>	—	0.500	ns

¹0.2 V_{cc} to 0.6 V_{cc}.

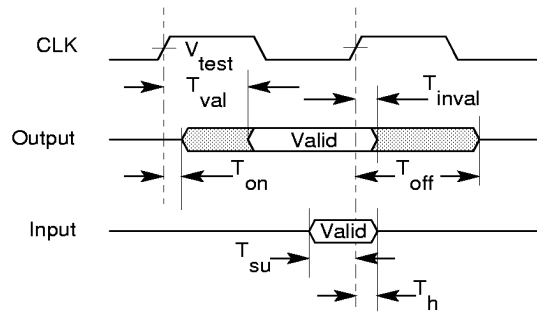
²Measured with 30-pF lumped load.

16.4 AC Timing Specifications

16.4.2 PCI Signal Timing Specifications

Figure 16–2 and Table 16–4 show the PCI signal timing specifications.

Figure 16–2 PCI Signal Timing Measurement Conditions



Note:
 V_{test} – 1.5 V for 5-V signals; 0.4 V_{cc} for 3.3-V signals

LJ-04739.A14

16.4 AC Timing Specifications

Table 16–4 PCI Signal Timing

Symbol	Parameter	Minimum	Maximum	Unit
T_{val}	CLK to signal valid delay—based signals ^{1,2,3}	2	11	ns
$T_{val(ptp)}$	CLK to signal valid delay—point-to-point ^{1,2,3}	2	12	ns
T_{on}	Float to active delay ^{1,2}	2	—	ns
T_{off}	Active to float delay ^{1,2}	—	28	ns
T_{su}	Input setup time to CLK—based signals ^{1,2,3}	7	—	ns
$T_{su(ptp)}$	Input setup time to CLK—point-to-point ^{1,2,3}	10, 12	—	ns
T_h	Input signal hold time from CLK ^{1,2}	0	—	ns

¹See Figure 16–2.

²All primary interface signals are synchronized to **p_clk**. All secondary interface signals are synchronized to **s_clk**.

³Point-to-point signals are **p_req_l**, **s_req_l<8:0>**, **p_gnt_l**, and **s_gnt_l<8:0>**.
Bused signals are **p_ad**, **p_cbe_l**, **p_par**, **p_perr_l**, **p_serr_l**, **p_frame_l**, **p_irdy_l**, **p_trdy_l**, **p_lock_l**, **p_devsel_l**, **p_stop_l**, **p_idsel**, **s_ad**, **s_cbe_l**, **s_par**, **s_perr_l**, **s_serr_l**, **s_frame_l**, **s_irdy_l**, **s_trdy_l**, **s_lock_l**, **s_devsel_l**, and **s_stop_l**.

16.4 AC Timing Specifications

16.4.3 Reset Timing Specifications

Table 16–5 shows the reset timing specifications for **p_rst_1** and **s_rst_1**.

Table 16–5 Reset Timing Specifications

Symbol	Parameter	Minimum	Maximum	Unit
T_{rst}	p_rst_1 active time after power stable	1	—	μ s
$T_{rst-clk}$	p_rst_1 active time after p_clk stable	100	—	μ s
$T_{rst-off}$	p_rst_1 active-to-output float delay	—	40	ns
T_{rrst}	s_rst_1 active after p_rst_1 assertion	—	40	ns
$T_{rrst-on}$	s_rst_1 active time after s_clk stable	100	—	μ s
T_{drrst}	s_rst_1 deassertion after p_rst_1 deassertion	20	25	Cycles
	p_rst_1 slew rate ¹	50	—	mV/ns

¹Applies to rising (deasserting) edge only.

16.4 AC Timing Specifications

16.4.4 gpio Timing Specifications

Table 16–6 shows the **gpio** timing specifications. See also Figure 16–2.

Table 16–6 gpio Timing Specifications

Symbol	Parameter	Minimum	Maximum	Unit
T_{vgpio}	s_clk -to- gpio output valid	2	12	ns
T_{gcn}	gpio float-to-active delay	2	—	ns
T_{goff}	gpio active-to-float delay	—	28	ns
T_{gsu}	gpio -to- s_clk setup time	7	—	ns
T_{gh}	gpio hold time after s_clk	0	—	ns
T_{gcvat}	s_clk -to- gpio<0> shift clock output valid	—	13.5	ns
T_{gcyt}	gpio<0> cycle time	30	∞	ns
T_{gsvat}	gpio<0> -to- gpio<2> shift control output valid	—	8	ns
T_{msu}	msk_in setup time to gpio<0>	15	—	ns
T_{mh}	msk_in hold time after gpio<0>	0	—	ns

16.4 AC Timing Specifications

16.4.5 JTAG Timing Specifications

Table 16–7 shows the JTAG timing specifications.

Table 16–7 JTAG Timing Specifications

Symbol	Parameter	Minimum	Maximum	Unit
T_{jff}	tck frequency	0	10	MHz
$T_{j\bar{p}}$	tck period	100	∞	ns
T_{jht}	tck high time	45	—	ns
T_{jlt}	tck low time	45	—	ns
T_{jrt}	tck rise time ¹	—	10	ns
T_{jft}	tck fall time ²	—	10	ns
$T_{j\bar{s}}$	tdi , tms setup time to tck rising edge	10	—	ns
T_{jh}	tdi , tms hold time from tck rising edge	25	—	ns
T_{jd}	tdo valid delay from tck falling edge ³	—	30	ns
T_{jfa}	tdo float delay from tck falling edge	—	30	ns

¹Measured between 0.8 V and 2.0 V.

²Measured between 2.0 V and 0.8 V.

³ $C_1 = 50$ pF.